

04-01-2010



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To the Director of the U.S. Patent and Trademark Office, please record the attached documents or the new address(es) below.

1. Name of conveying party(ies)

Zakaryae Fathi
James E. Clayton

2. Name and address of receiving party(ies)

Name: Microelectronics Assembly technologies, Inc.

Internal Address: _____

Street Address: 104 T. W. Alexander Dr.

City: Research Triangle Park

State: NC

Country: USA Zip: 27709

Additional name(s) & address(es) attached? ☐ Yes ☐ No

3. Nature of conveyance/Execution Date(s):

Execution Date(s) March 22, 2010

- ☒ Assignment ☐ Merger
☐ Security Agreement ☐ Change of Name
☐ Joint Research Agreement
☐ Government Interest Assignment
☐ Executive Order 9424, Confirmatory License
☐ Other _____

4. Application or patent number(s):

☐ This document is being filed together with a new application.

A. Patent Application No.(s)

12/317,753
12/317,754
12/317,757
12/317,890
12/317 892

B. Patent No.(s)

Additional numbers attached? ☐ Yes ☐ No

5. Name and address to whom correspondence concerning document should be mailed:

Name: Robert J. Lauf

Internal Address: _____

Street Address: 998 W. Outer Dr.

City: Oak Ridge

State: TN Zip: 37830

Phone Number: 865-483-8798

Fax Number: _____

Email Address: rlauf@bellsouth.net

6. Total number of applications and patents involved: 5

7. Total fee (37 CFR 1.21(h) & 3.41) \$ 200

- ☐ Authorized to be charged by credit card
☐ Authorized to be charged to deposit account
☒ Enclosed
☐ None required (government interest not affecting title)

8. Payment Information

a. Credit Card Last 4 Numbers _____
Expiration Date _____

b. Deposit Account Number _____

Authorized User Name 00000004 12317753

01 FC:8021

9. Signature:

Robert J. Lauf

Signature

3/22/2010
Date

Robert J. Lauf

Name of Person Signing

Total number of pages including cover sheet, attachments, and documents: 5

Documents to be recorded (including cover sheet) should be faxed to (571) 273-0140, or mailed to:
Mail Stop Assignment Recordation Services, Director of the USPTO, P.O.Box 1450, Alexandria, V.A. 22313-1450

ASSIGNMENT

WHEREAS, I the below-named inventor whose residence and post office are as stated below, have invented certain new and useful improvements in electronic modules represented by the following U.S. Patent Application(s):

12/317,753 "Thin Multichip Flex-Module" Clayton et al.
12/317,754 "Thin Multichip Flex-Module" Clayton et al.
12/317,757 "Thin Multichip Flex-Module" Clayton et al.
12/317,890 "Thin Multichip Flex-Module" Clayton et al.
12/317,892 "Thin Multichip Flex-Module" Clayton et al.

(hereinafter referred to as "Subject Invention") for which applications for United States Letters Patent have been executed by me, and

WHEREAS, MICROELECTRONICS ASSEMBLY TECHNOLOGIES, INC., a corporation in the State of North Carolina, having an office at 104 T.W. Alexander Drive, Research Triangle Park, NC 27709, hereinafter referred to as "ASSIGNEE," is desirous of acquiring the entire right, title and interest of the undersigned in the Subject Invention and to any Letters Patent that may be granted therefor in the United States of America and in any and all foreign countries.

NOW, THEREFORE, in accordance with the terms of my employment agreement with ASSIGNEE and for good and valuable consideration, the receipt of which is hereby acknowledged, I hereby assign to ASSIGNEE my entire right, title and interest in the Subject Invention to all rights of priority thereto pursuant to the International Convention for the Protection of Industrial Property, and in any Letters Patent on the Subject Invention that may be granted in the United States of America and in any and all foreign countries, including any and all Letters Patent that are divisions, reissues, continuations, substitutions or extensions of any Letters Patent or applications therefor on the Subject Invention.

I hereby authorize and request the Commissioner of the United States Patent and Trademark Office and the officials of any and all foreign countries to issue any and all of said Letters Patent, when granted, to the ASSIGNEE.

Further, I hereby agree to communicate to said ASSIGNEE or its representatives any facts known to me respecting said Subject Invention, to testify in any legal proceedings, sign all lawful papers, execute all divisional, continuation, substitution, renewal and reissue applications, to execute all necessary assignment papers to cause any and all of said Letters Patent to be issued to said ASSIGNEE, and to make all

rightful oaths and generally do everything possible to aid said ASSIGNEE and its representatives to obtain and enforce proper protection for said Subject Invention in the United States of America and in any and all foreign countries.

I further agree that the terms, covenants and conditions of this assignment shall inure to the benefit of ASSIGNEE, its successors, assigns, and legal representatives, and shall be binding on me, my heirs, legal representatives, and assigns.

Full name of inventor: James E. Clayton

Signature: James E. Clayton Date: March 22, 2010

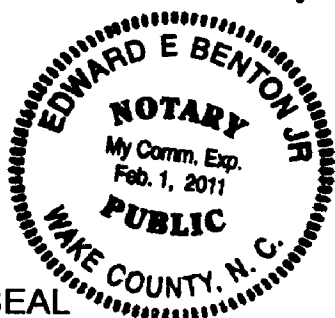
Residence: 2505 Happy Lane, Raleigh, NC 27614

Post Office Address: 2505 Happy Lane, Raleigh, NC 27614

State of North Carolina)
County of Wake)

On this 22 day of March, 2010, before me, a Notary Public in and for the County and State aforesaid, appeared INVENTOR to me personally known to be the same person whose name is subscribed to the foregoing instrument, and acknowledged that he executed said instrument as his free and voluntary act and for the uses and purposes therein expressed.

WITNESS my hand and seal the day and year last above given.



Edward E. Benton Jr.
Notary Public

SEAL
My Commission Expires: 2-1-2011

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I hereby authorize and request the Commissioner of the United States Patent and Trademark Office and the officials of any and all foreign countries to issue any and all of said Letters Patent, when granted, to the ASSIGNEE.

Further, I hereby agree to communicate to said ASSIGNEE or its representatives any facts known to me respecting said Subject Invention, to testify in any legal proceedings, sign all lawful papers, execute all divisional, continuation, substitution, renewal and reissue applications, to execute all necessary assignment papers to cause any and all of said Letters Patent to be issued to said ASSIGNEE, and to make all

rightful oaths and generally do everything possible to aid said ASSIGNEE and its representatives to obtain and enforce proper protection for said Subject Invention in the United States of America and in any and all foreign countries.

I further agree that the terms, covenants and conditions of this assignment shall inure to the benefit of ASSIGNEE, its successors, assigns, and legal representatives, and shall be binding on me, my heirs, legal representatives, and assigns.

Full name of inventor: Zakaryae Fathi

Signature: _____

Date: 3-22-2010

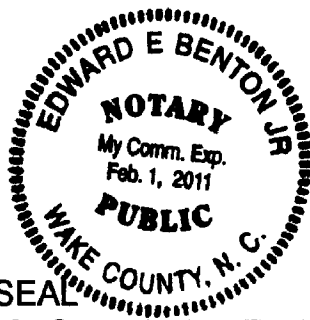
Residence: 2409 Dunn Road, Raleigh, NC 27614

Post Office Address: 2409 Dunn Road, Raleigh, NC 27614

State of North Carolina)
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WITNESS my hand and seal the day and year last above given.



Edward E. Benton, Jr.
Notary Public

SEAL
My Commission Expires: 2-1-2011